SDLS107 - OCTOBER 1976 - REVISED MARCH 1988

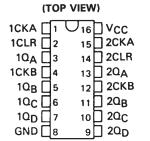
- Dual Versions of the Popular '90A, 'LS90 and '93A, 'LS93
- '390, 'LS390 . . . Individual Clocks for A and B Flip-Flops Provide Dual ÷ 2 and ÷ 5 Counters
- '393, 'LS393... Dual 4-Bit Binary Counter with Individual Clocks
- All Have Direct Clear for Each 4-Bit Counter
- Dual 4-Bit Versions Can Significantly Improve System Densities by Reducing Counter Package Count by 50%
- Typical Maximum Count Frequency . . . 35 MHz
- Buffered Outputs Reduce Possibility of Collector Commutation

description

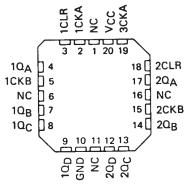
Each of these monolithic circuits contains eight master-slave flip-flops and additional gating to implement two individual four-bit counters in a single package. The '390 and 'LS390 incorporate dual divide-by-two and divide-by-five counters, which can be used to implement cycle lengths equal to any whole and/or cumulative multiples of 2 and/or 5 up to divide-by-100. When connected as a bi-quinary counter, the separate divide-by-two circuit can be used to provide symmetry (a square wave) at the final output stage. The '393 and 'LS393 each comprise two independent four-bit binary counters each having a clear and a clock input. N-bit binary counters can be implemented with each package providing the capability of divide-by-256. The '390, 'LS390, '393, and 'LS393 have parallel outputs from each counter stage so that any submultiple of the input count frequency is available for system-timing signals.

Series 54 and Series 54LS circuits are characterized for operation over the full military temperature range of -55°C to 125°C; Series 74 and Series 74LS circuits are characterized for operation from 0°C to 70°C.

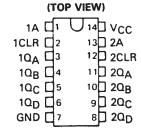
SN54390, SN54LS390 . . . J OR W PACKAGE SN74390 . . . N PACKAGE SN74LS390 . . . D OR N PACKAGE



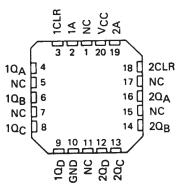
SN54LS390 . . . FK PACKAGE (TOP VIEW)



SN54393, SN54LS393 . . . J OR W PACKAGE SN74393 . . . N PACKAGE SN74LS393 . . . D OR N PACKAGE



SN54LS393 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection



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'390, 'LS390
BCD COUNT SEQUENCE
(EACH COUNTER)
(See Note A)

COUNT		συτ	PUT									
COONT	σ_{D}	σc	σ_{B}	QA								
0	L	L.	L	L								
1	L	L	L	н								
2	L	L	Н	ᆸ								
3	L	L	Н	н								
4	L	Н	L	ᅵ								
5	L	Н	L	н								
6	L	Н	Н	ᅵᅵ								
7	L	Н	Н	н								
8	н	L	L	L								
9	Н	L	L	Н								

FUNCTION TABLES
'390, 'LS390
BI-QUINARY (5-2)
(EACH COUNTER)
(See Note B)

COLUNIT		OUT	PUT	
COUNT	QΑ	α_{D}	αc	$oldsymbol{Q}_{B}$
0	L	L	L	٦
1	L	L	L	н
2	L	L	Н	L
3	L	L	Н	н
4	L	Н	L	L
5	н	L	L	L
6	н	L	L	Н
7	н	L	Н	L
8	н	L	Н	н
9	Н	Н	L	L

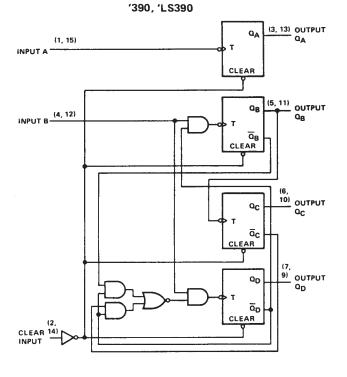
'393, 'LS393 COUNT SEQUENCE (EACH COUNTER)

COUNT		OUT	PUT	
CODIVI	a_{D}	αc	Q_{B}	QA
0	L	L	L	L
1	L	L	L	н
2	L	L	Н	L
3	L	L	Н	н
4	L	Н	L	L
5	L	Н	L	н
6	L	н	Н	L
7	L	Н	Н	-н
8	н	L	L	ᅵᅵ
9	н	L	L	н
10	н	L	н	L
11	н	L	Н	н
12	н	Н	L	L
13	н	Н	L	н
14	н	Н	Н	L
15	н	н		

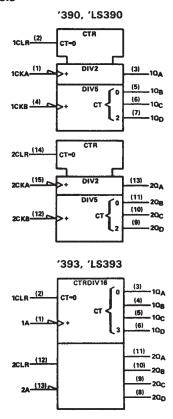
NOTES: A. Output QA is connected to input B for BCD count,

- B. Output Q_D^{\frown} is connected to input A for bi-quinary
 - count.
- C. H = high level, L = low level.

logic diagrams (positive logic)



logic symbols†

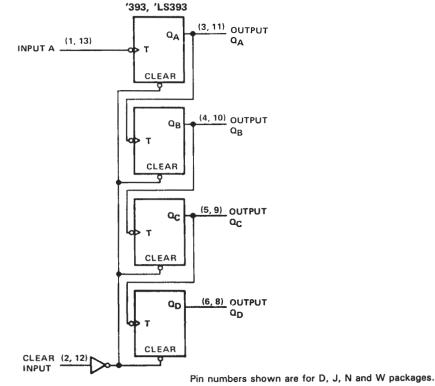


[†]These symbols are in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

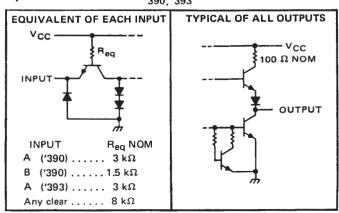




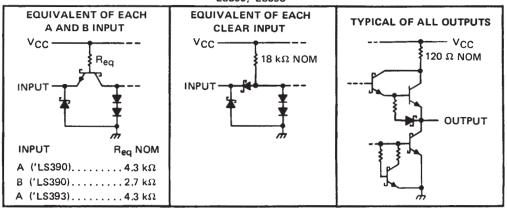


schematics of inputs and outputs

'390, '393



'LS390, 'LS393





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)	
Input voltage	
Operating free-air temperature range: SN54390, SN54393	
	0°C to 70°C
	-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

		- 1	SN5439 SN5439			UNIT		
		MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V _{CC}		4.5	5	5.5	4.75	5	5.25	٧
High-level output current, IOH				-800			-800	μΑ
Low-level output current, IOL				16			16	mA
Count francisco f	A input	0		25	0		25	MHz
Count frequency, f _{count}	B input	0		20	0		20	IVIDZ
	A input high or low	20			20			
Pulse width, t _W	B input high or low	25			25			ns
	Clear high	20			20		•	1
Clear inactive-state setup time, t _{su}	•	25↓			25↓			ns
Operating free-air temperature, TA		-55		125	0		70	°C

 $[\]downarrow$ The arrow indicates that the falling edge of the clock pulse is used for reference.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	D		7507.00V	NTIONO!		′390			′393		
	PARAMETER		TEST CONE	NI IONS.	MIN	TYP‡	MAX	MIN	TYP [‡]	MAX	UNIT
VIH	High-level input voltage				2			2			V
VIL	Low-level input voltage						0.8			0.8	V
VIK	Input clamp voltage		VCC = MIN, I	≖ –12 mA			-1.5			-1.5	V
Vон	High-level output voltage		V _{CC} = MIN, V V _{IL} = 0.8 V, I _C		2.4	3.4		2.4	3.4		V
VOL	Low-level output voltage		V _{CC} = MIN, V V _{IL} = 0.8 V, I _C	***		0.2	0.4		0.2	0.4	V
11	Input current at maximum input voltage		V _{CC} = MAX, V	j = 5.5 V			1			1	mA
		Clear	,				40			40	
ин	High-level input current	Input A	V _{CC} = MAX, V	j = 2.4 V			80			80	μΑ
		Input B					120				
		Clear					1			-1	
11L	Low-level input current	Input A	V _{CC} = MAX, V	j = 0.4 V			-3.2			-3.2	mA
		Input B					-4.8				
100	Short-circuit output current §		V-0 = MAY	SN54'	-20		57	-20		-57	mA
los	Short-circuit output current's		V _{CC} = MAX	SN74'	-18		-57	-18		-57	IIIA
Icc	Supply current		V _{CC} = MAX, Se	ee Note 2		42	69		38	64	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: ICC is measured with all outputs open, both clear inputs grounded following momentary connection to 4.5 V, and all other inputs grounded.



 $^{^{\}ddagger}$ All typical values are at V_{CC} = 5 V, T_A = 25 °C.

[§] Not more than one output should be shorted at a time.

The QA outputs of the '390 are tested at IOL = 16 mA plus the limit value for IIL for the B input. This permits driving the B input while maintaining full fan-out capability.

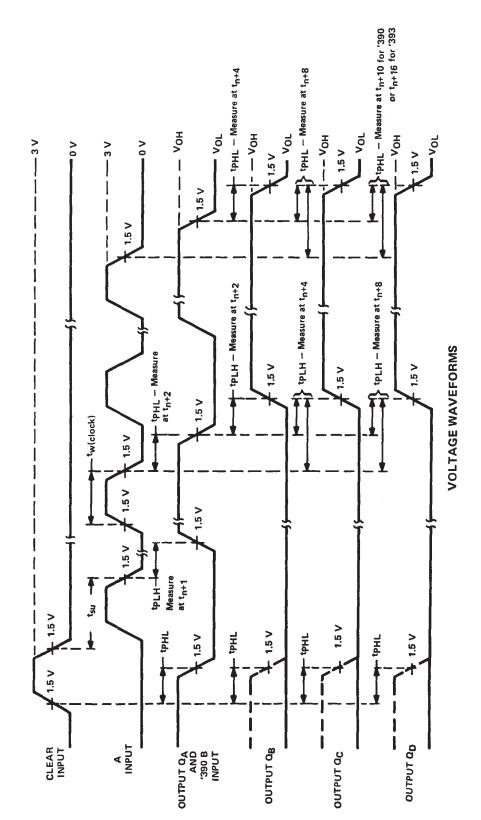
SDLS107 - OCTOBER 1976 - REVISED MARCH 1988

switching characteristics, V_{CC} = 5 V, T_A = 25°C

242445752	FROM	то	TEST CONDITIONS		′390			′393		UNIT
PARAMETER	(INPUT)	(OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	Civil
,	Α	QΑ		25	35		25	35		MHz
f _{max}	В	QB		20	30					141112
^t PLH	А	0	1		12	20		12	20	ns
tPHL		Q _A			13	20		13	20	1113
^t PLH		Q _C of '390	Cլ=15 pF,		37	60		40	60	ns
tPHL.	Α	Q _D of '393	R _L = 400 Ω,		39	60		40	60	1113
tPLH .	В	_	See Note 3		13	21				ns
t _{PHL}	В	QB	and		14	21				115
t _{PLH}	В	0 -	Figure 1		24	39				ns
[†] PHL	P	αc			26	39				113
^t PLH	В	0-]		13	21				ns
^t PHL	B	α_{D}			14	21				113
t _{PHL}	Clear	Any			24	39		24	39	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

PARAMETER MEASUREMENT INFORMATION



NOTE A: Input pulses are supplied by a generator having the following characteristics t_r < 5 ns, t_f < 5 ns, PRR = 1 MHz, duty cycle = 50%, Z_{out} ≈ 50 ohms.

FIGURE 1



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)									 ٠.							. 7 V
Clear input voltage																
Any A or B clock input voltage									 							5.5 V
Operating free-air temperature range:	SN54	LS39	0, S	N54	LS39	3							-5	5°C	to	125°C
	SN74	LS39	0, S	N74	LS39	3								0°0	C to	70°C
Storage temperature range									 				-6	5°C	to	150°C
NOTE 1: Voltage values are with respect to netw																

recommended operating conditions

		_	N54LS			N74LS3 N74LS3		UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V _{CC}		4.5	5	5.5	4.75	5	5.25	٧
High-level output current, IOH				-400			-400	μΑ
Low-level output current, IOL				4			8	mA
0	A input	0		25	0		25	MHz
Count frequency, f _{count}	B input	0		12.5	0		12.5	IVIFIZ
	A input high or low	20			20			
Pulse width, tw	B input high or low	40			40			ns
	Clear high	20			20			1
Clear inactive-state setup time, t _{su}		25‡			25↓			ns
Operating free-air temperature, TA		55		125	0		70	°C

The arrow indicates that the falling edge of the clock pulse is used for reference.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

							SN54L	S'		UNIT		
	PARAMETER		TES	T CONDITIONS		MIN	TYP‡	MAX	MIN	TYP‡	MAX	CIVIT
VIH	High-level input voltage					2			2			V
VIL	Low-level input voltage							0.7			0.8	V
VIK	Input clamp voltage		VCC = MIN,	I _I = -18 mA				-1.5			-1.5	V
Vон	High-level output voltage	1	V _{CC} = MIN, V _{IL} = V _{IL} max,	V _{IH} = 2 V, I _{OH} = -400 μA		2.5	3.4		2.7	3.4		V
.,			V _{CC} = MIN,	V _{IH} = 2 V,	IOL = 4 mA¶		0.25	0.4		0.25	0.4	V
VOL	Low-level output voltage		V _{IL} = 0.8 V,		IOL = 8 mA¶					0.35	0.5	
	Input ourroat at	Clear			V _I = 7 V			0.1			0.1	
Ц	Input current at maximum input voltage	Input A	V _{CC} = MAX		V ₁ = 5.5 V			0.2			0.2	mA
	maximum input vortage	Input B			V1 - 3.5 V			0.4			0.4	
		Clear						0.02	ļ		0.02	1
ΉΗ	High-level input current	Input A	$V_{CC} = MAX$,	$V_1 = 2.7 V$				0.1			0.1	mA
		Input B						0.2			0.2	
		Clear						-0.4			-0.4	1
HL	Low-level input current	Input A	VCC = MAX,	V1 = 0.4 V				-1.6			-1.6	4
		Input B						-2.4			-2.4	<u> </u>
IOS	Short-circuit output curi	rent§	V _{CC} = MAX			-20		-100	-20		-100	
Lan	Supply ourrent		VCC = MAX,		'LS390		15	26		15		-l mA
Icc	Supply current		See Note 2		'LS393		15	26		15	26	

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: I_{CC} is measured with all outputs open, both clear inputs grounded following momentary connection to 4.5 V, and all other inputs grounded.



 $^{^{\}ddagger}$ All typical values are at V_{CC} = 5 V, T_A = 25 °C.

[§] Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

¹ The QA outputs of the LS390 are tested at IOL = MAX plus the limit value for IIL for the clock B input. This permits driving the clock B input while maintaining full fan-out capability.

SN54390, SN54LS390, SN54393, SN54LS393 SN74390, SN74LS390, SN74393, SN74LS393 DUAL 4-BIT DECADE AND BINARY COUNTERS SDLS107 - OCTOBER 1976 - REVISED MARCH 1988

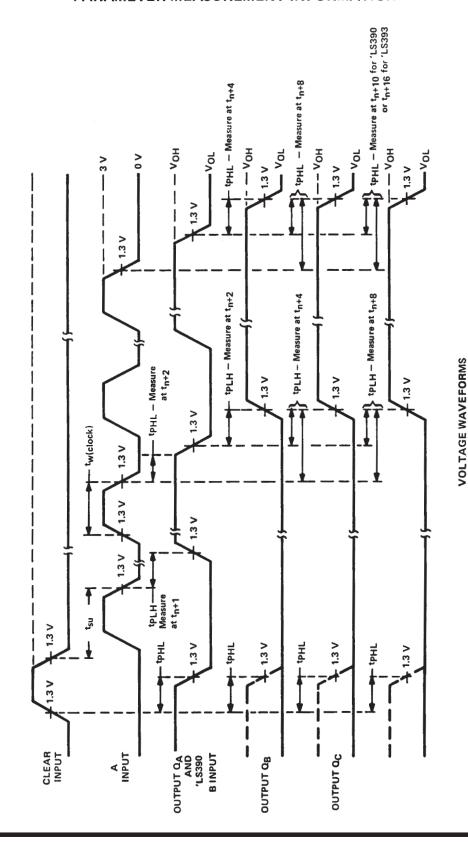
switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ} \text{ C}$

DADAMETED	FROM	то	7507 00MD1710M0		'LS390			'LS393		
PARAMETER	(INPUT)	(OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNIT
	А	QA		25	35		25	35		MHz
f _{max}	В	QΒ]	12.5	20					IVITIZ
tPLH	A	0.			12	20		12	20	
^t PHL	7 ^	Q _A			13	20		13	20	ns
^t PLH	A	QC of 'LS390	C _L = 15 pF,		37	60		40	60	
^t PHL	1_^	Q _D of 'LS393	$R_{L} = 2 k\Omega$,		39	60		40	60	ns
^t PLH	В	0-	See Note 4 and Figure 2		13	21				
tPHL	1 -	QΒ			14	21				ns
tPLH .	В	0-			24	39				
tPHL.	1 6	σC			26	39				ns
^t PLH	В	0-			13	21				
^t PHL	1	σD			14	21				ns
tPH L	Clear	Any			24	39		24	39	ns

NOTE 4: Load circuits and voltage waveforms are shown in Section 1.



PARAMETER MEASUREMENT INFORMATION



NOTE A: Input pulses are supplied by a generator having the following characteristics t₁< 15 ns, t₁< 6 ns, PRR = 1 MHz, duty cycle = 50 %,

 $Z_{out} \approx 50$ ohms.

FIGURE 2



23-Mar-2012

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
7802601EA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Call TI	
7802601FA	ACTIVE	CFP	W	16	1	TBD	Call TI	Call TI	
7802601FA	ACTIVE	CFP	W	16	1	TBD	Call TI	Call TI	
JM38510/32701B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
JM38510/32701B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
JM38510/32701BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
JM38510/32701BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
JM38510/32702B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
JM38510/32702B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
JM38510/32702BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
JM38510/32702BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
JM38510/32702BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	
JM38510/32702BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	
JM38510/32702SCA	ACTIVE	CDIP	J	14	25	TBD	A42	N / A for Pkg Type	
JM38510/32702SCA	ACTIVE	CDIP	J	14	25	TBD	A42	N / A for Pkg Type	
JM38510/32702SDA	ACTIVE	CFP	W	14	25	TBD	A42	N / A for Pkg Type	
JM38510/32702SDA	ACTIVE	CFP	W	14	25	TBD	A42	N / A for Pkg Type	
M38510/32701B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
M38510/32701B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
M38510/32701BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
M38510/32701BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
M38510/32702B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
M38510/32702B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
M38510/32702BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
M38510/32702BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
M38510/32702BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	
M38510/32702BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	
M38510/32702SCA	ACTIVE	CDIP	J	14	25	TBD	A42	N / A for Pkg Type	
M38510/32702SCA	ACTIVE	CDIP	J	14	25	TBD	A42	N / A for Pkg Type	
M38510/32702SDA	ACTIVE	CFP	W	14	25	TBD	A42	N / A for Pkg Type	



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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
M38510/32702SDA	ACTIVE	CFP	W	14	25	TBD	A42	N / A for Pkg Type	
SN54393J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	
SN54393J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	
SN54LS390J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SN54LS390J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SN54LS393J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SN54LS393J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SN74390N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	
SN74390N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	
SN74393N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	
SN74393N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	
SN74393N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	
SN74393N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	
SN74LS390D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS390D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS390DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS390DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS390DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS390DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS390N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74LS390N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74LS390N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	
SN74LS390N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	
SN74LS390NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74LS390NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74LS390NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	



23-Mar-2012

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
SN74LS390NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS390NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS390NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS390NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS390NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS393D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS393D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS393DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS393DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS393DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS393DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS393DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS393DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS393DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS393DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS393DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS393DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS393J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	
SN74LS393J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	



23-Mar-2012

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login
SN74LS393N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74LS393N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74LS393N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	
SN74LS393N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	
SN74LS393NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74LS393NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74LS393NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS393NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS393NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS393NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS393NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS393NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SNJ54393J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	
SNJ54393J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	
SNJ54393W	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI	
SNJ54393W	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI	
SNJ54LS390FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54LS390FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54LS390J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SNJ54LS390J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SNJ54LS390W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	
SNJ54LS390W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	
SNJ54LS393FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54LS393FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54LS393J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SNJ54LS393J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SNJ54LS393W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	



PACKAGE OPTION ADDENDUM

23-Mar-2012

Orderable Device	Status ⁽¹⁾	Package Typ	e Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
SNJ54LS393W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF SN54393, SN54LS390, SN54LS393, SN54LS393-SP, SN74393, SN74LS390, SN74LS393:

Catalog: SN74393, SN74LS390, SN74LS393, SN54LS393

Military: SN54393, SN54LS390, SN54LS393

Space: SN54LS393-SP

NOTE: Qualified Version Definitions:





23-Mar-2012

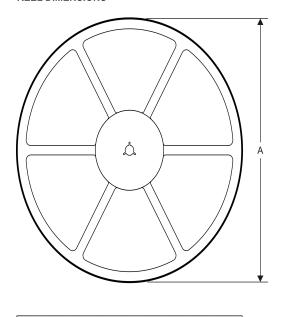
- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications
- Space Radiation tolerant, ceramic packaging and qualified for use in Space-based application

PACKAGE MATERIALS INFORMATION

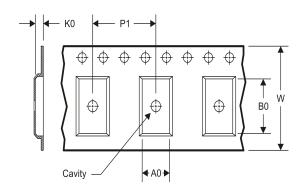
www.ti.com 14-Jul-2012

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

All difficultions are florifinal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS390NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74LS393DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LS393NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS390NSR	SO	NS	16	2000	367.0	367.0	38.0
SN74LS393DR	SOIC	D	14	2500	367.0	367.0	38.0
SN74LS393NSR	SO	NS	14	2000	367.0	367.0	38.0

14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK

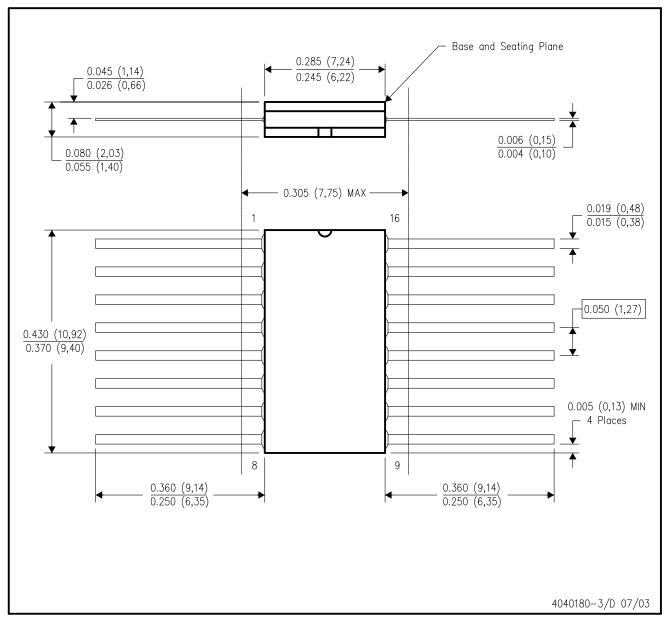


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC



FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



D (R-PDS0-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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